Form Mod 44	2000 & U.S. DEPARTM		CASE NO. 1717 P2	SERIA	L NO. 09/512,7	34
	MON DISCLOSURE	STATEMENT	APPLICANT Chen et al.			
	// lan annunul abanda if mana		FILING DATE	GRO	UP	
	(Use several sheets if neces	sary)	Eebruary 18, 2000	No	t yet assigne	∋d
		U.S. PATEN	IT DOCUMENTS			
*EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
		EODEIGN DAT	ENT DOCUMENTS			
				01.400	OLUBOL AGG	TRANSLATION
	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	YES NO
	OTHER (Including Author, T	itle, Date, Pertinent Pages, Etc	.)		
	Simpson et al. "The Ele Abstract No. 727, The	ectrical Integrity of Cor Electrochemical Cher	oper Plated Wafers Using a Novel P nical Society, October 17-22, 1999	Plating-Bath	Chemistry"	
EXAMINER			DATE CONSIDERED			
	A > 8		70/16/0			
•	EXAMINER: Initial if reference consideration conformance and in the	lered, whether or not citati not considered. Include co	on is in conformance with MPEP 609. Dra opy of this form with next communication to	aw line through applicant.	n citation if not it	า

LIST OF ART CITED BY APPLICANT (PTO-1449)				ATTY. DOCKET NO. 103864-1101		SERIAL NO. 09/512,734			
				APPLICANT Lasher et al.					
				FILING DATE February 24, 2000		GROUP 3721			
J.S. PATENT	DOCUMENTS	P. A.	attic.						
XAMINER'S NIT I ALS	PATENT NO.	DATE ~~	THE THE PROPERTY OF THE PROPER		CLASS	SUBCLASS	FILING DAT		
110	3,139,713	1964	Merrill et al.		53	55			
	4,013,192	1977	Pillon		221	7			
1 1	4,112,332	1978	Veith et al.		315	169			
\triangle	4,171,065	1979	Hurst		221	2			
•	4,664,289	1987	Shimizu et al.		221	2 = =			
Ĺ	4,695,954	1987	Rose et al.		364	413 &	121		
•	4,869,394	1989	Hurst		221	7 -	\sim		
\	4,847,764	1989	Halvorson		364	413.			
	4,953,745	1990	Rowlett, Jr.		221	5 - 22			
	5,208,762	1993	Charhut et al.	Charhut et al.		ئن	Ö		
<u> </u>	5,348,061	09/94	Riley et al.		221	2x ≈	12/92		
, [4,674,259	06/87	Hills		53	501x			
4	4,018,358	04/77	Johnson et al.		221	7			
-	3,677,437	07/72	Haigler		221	7			
T	3,193,196	07/65	Merrill et al.		53	501x			
•	2,618,420	11/52	Levine		53	505			
ŀ	4,733,362	1988	Haraguchi		GO8H	5/00			
1	4,870,799	10/89	Bergerioux et	al	53	168			
4	5,502,944	04/96	Kraft et al.		53	168			
·Ì	5,481,855	01/96	Yuyama		53	493			
,	5,097,652	03/92	Inamura		53	168			
-	5,884,806	03/23/99	Boyer et al.		221	75	12/02/96		
1	5,638,417	06/10/97	Boyer et al.		377	7	05/06/96		
Al.	5,671,262	09/23/97	Boyer et al.		377	11	05/06/96		
# /	5,907,493	05/25/99	Boyer et al.		364	479.01	01/31/97		
	TENT DOCUM	ENTS							
KAMINER'S	PATENT NO.	DATE	COUNTRY		CLASS	SUBCLASS	Translation Yes No		
	WO98/09598		PCT/US/97/15	5472					
THER ART	(Including Author)			· · · · · · · · · · · · · · · · · · ·					
15	"Baker Lockou	ts: Persisten	ce Pays Off", Qua	ality Bulletin, Mar	<u>ch 1993</u>	·····	· •		
XAMINER			r	DATE CONSIDER	ED				

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.

LIST OF ART CITED BY APPLICANT				ATTY. DOCKET NO. 103864-1101 SERIAL NO. 09/512,734 APPLICANT			
(PTO-14	49)	OCTE OCT	1 1 0 2000 CO	Lasher et al. FILING DATE GROUP February 24, 2000 3721			
TIC DATENT	DOCUMENTS	Pa	DEMORY	· · · · · · · · · · · · · · · · · · ·	- · · · · · · · · · · · · · · · · · · ·		
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME		CLASS	SUBCLASS	FILING DATE
	4,542,808	09/24/85	Lloyd et al.		186	56	06/30/83
1.9	4,567,988	02/04/86	Weibel		209	564	04/22/83
4	4,672,553	06/09/87	Goldberg		364	478	04/17/86
0	4,111,332	09/05/78	Hurst et al.		221	7	12/16/74
A -	4,874,281	10/17/89	Bergerioux et	al.	414	285	03/27/87
						TECHNOLUMY DENTILLE BYDO	REOE VI
	ATENT DOCUM					Tara	7D
EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY		CLASS	SUBCLASS	Translation Yes No
OTHER ART	(Including Auth	or, Title, Date	e, Pertinent Page	es, Etc.)			
EXAMINER		0	I	DATE CONSIDER	ED /6/	15/01	

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.